										
FORM PTO-892			U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		SERIAL NO. 09/834,696	GROUI UNIT N/A	PART	ATTACHMENT TO PAPER NO.		
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	C	5,136,366	8/4/92	Worp et al.		357	72			
	D	5,341,564	8/30/94	Akhavain et al.		29	832		ļ	
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	F	5,397,921	3/14/95	Karnezos		257	779			
T	G	5,355,283	10/11/94	Marrs et al.		361	760		<u> </u>	
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